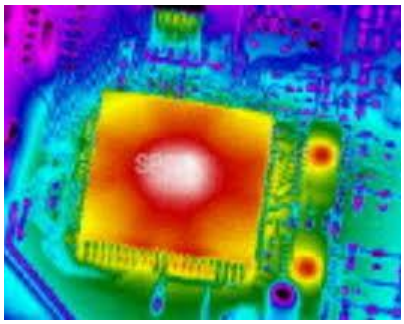
# ΔΙΑΛΕΞΗ

Το Εργαστήριο Ηλεκτρονικής σας προσκαλεί στην διάλεξη του καθηγητή του πολυτεχνείου του Βουκουρεστίου **Dr. Norocel Dragoş Codreanu,** που θα δοθεί : Τετάρτη 6 Σεπτεμβρίου 2017 και ώρα 12.30 στην αίθουσα Γενικών Συνελεύσεων του Τμήματος Φυσικής (4ος όροφος - μικρό ασανσέρ ανατολικά)

με τίτλο:

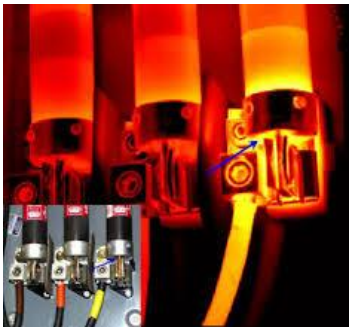
**Thermal Management of Electronic Modules & Systems based on Infrared Thermovision/Thermography**

## Course overview



The course provides to participants an overview regarding the real thermal management in electronics based on infrared thermovision/thermography. It provides an introduction to infrared (IR) technology and covers the fundamentals of thermal imaging. Topics include fundamentals of thermal imaging, elements that influence the image quality and interpretations of various thermal images. The course develops fluency with the relevant IR terminology, concepts and usage of thermal IR cameras. Finally, the participants will gain capabilities of using IR cameras and performing professional thermal measurements of electronic modules and systems.

## Who should attend?



The course is destined to electrical and electronics students (B. Sc., M. Sc., Ph. D.) involved in electronic design, professors in the field of electronics and electronic packaging, technical and scientific staff of the university who wish to get a comprehensive overview of thermal management for electronic modules & systems and of infrared thermovision/thermography. The course is focused on various practical engineering aspects and, due to a large number of practical examples which can be directly applied during the current work, is addressed also to researchers and engineers involved in R&D activities and manufacturing/testing of high performance electronic products.

## *CV*

**Norocel-Dragoş Codreanu,** Ph.D., is full professor at "Politehnica" University of Bucharest (UPB), Romania, Faculty of Electronics, Telecommunications and Information Technology, Department of Electronics Technology and Reliability (TEF), being currently the executive manager of the UPB university research centre "Center for Technological Electronics and Interconnection Techniques" (UPB-CETTI). He has received his formal education at UPB, obtaining his M.S. in radio-communications in 1988. He has joined UPB in 1992, where he has received the Ph.D. degree in 1999, after a research period at Budapest University of Technology & Economics, Hungary. He is specialist in electronic packaging and advanced technologies, being focused on CAE-CAD-CAM for electronic modules/assemblies development, high-speed/high-frequency PCB/MCM-L design and manufacturing, full-wave electromagnetic modelling and simulation of planar structures, printed circuit/wiring board fabrication processes, electronic assembling technologies and heterogeneous integration (including Lead-Free issues, fine-pitch/high-density interconnections, package-on-package, system-in-package, thermal management, a.s.o. Additionally, he has expertise in IR thermovision/thermography for electrical/electronic systems and in standardization for the electronics industry. He has been senior researcher or manager for more than 25 national and international projects focused on innovation, technology transfer, education and partnerships with industry. He has authored more than 150 scientific contributions/reports/articles and papers (author or co-author) and 7 text books (author or co-author) in electronic packaging and related fields.